

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chopra et. al.

Serial No.: Not Yet Assigned

Filed: July 14, 2003

For: SLURRY FOR USE WITH FIXED-ABRASIVE POLISHING PADS IN POLISHING SEMICONDUCTOR DEVICE CONDUCTOR STRUCTURES THAT INCLUDE COPPER AND TUNGSTEN

Confirmation No.: Unknown

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 2269-4373.2US
(00-0036.02/US)

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Person making Deposit: Matthew Wooton

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The present application is a continuation of application Serial No. 09/651,808, filed August 30, 2000, pending.

Pursuant to M.P.E.P. 2001.06(b), the Examiner is respectfully requested to consider the information of record in the prior application, and to confirm in the first Office Action on the merits that such art has in fact been reviewed. A PTO-1449 or PTO/SB/08 form listing all of the information of record in the prior application is enclosed herewith.

Attorney Docket No. 2269-4373.2US

This Information Disclosure Statement is filed within three (3) months of the filing date of the above-identified application, and no certification pursuant to 37 C.F.R. § 1.97(c) or a fee pursuant to 37 C.F.R. 1.17(p) is required.

Respectfully submitted,



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Date: July 14, 2003

BGP/dlm:djp

Enclosures: Form PTO-1449 or PTO/SB/08

Document in ProLaw

Form PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)		Docket Number (Optional) 4373.2US (00-0036.02/US)	Application Number Not Yet Assigned
		Applicant Chopra et al.	
		Filing Date July 14, 2003	Group Art Unit Unknown

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5,780,358	07/1998	Zhou et al.			
	5,836,806	11/1998	Cadien et al.			
	5,840,629	11/1998	Carpio			
	5,846,398	12/1998	Carpio			
	5,863,307	01/1999	Zhou et al.			
	5,897,375	04/1999	Watts et al.			
	5,954,975	09/1999	Cadien et al.			
	5,954,997	09/1999	Kaufman et al.			
	5,985,748	11/1999	Watts et al.			
	6,001,730	12/1999	Farkas et al.			
	6,046,099	04/2000	Cadien et al.			
	6,083,419	07/2000	Grumbine et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
	WO 98/49723	11/1998	PCT				
	WO 00/00561	01/2000	PCT				
	WO 00/28586	05/2000	PCT				
	WO 01/21724 A1	03/2001	PCT				

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

	Lee, Michael G., et al., "Planarization of Copper/Polyimide for Multilevel Interconnects by Chemical Mechanical Polishing (CMP)," VMIC (1996), pp. 395-397, Proceedings of 13th Internat'l. VLSI Multilevel Interconnection Conf., Santa Clara, CA, June 18-20, 1996.
	Stavreva, Z., et al., "Chemical-Mechanical Polishing of Copper for Interconnect Formation," Microelectronic Eng., Vol. 33 (1997), pp. 249-257.
	Seung-Mahn Lee, et al., "Study of Slurry Chemistry in Chemical Mechanical Polishing (CMP) of Copper," Database Chemabs Online!, Chemical Abstracts, Columbus, Ohio, Proceedings--Electrochemical Society (2000).

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

Form PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)			Docket Number (Optional) 4373.2US (00-0036.02/US)	Application Number Not Yet Assigned			
			Applicant Chopra et al.				
			Filing Date July 14, 2003	Group Art Unit Unknown			
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS		
	6,063,306	05/2000	Kaufman et al.				
	6,083,840	07/2000	Mravic et al.				
	6,100,197	08/2000	Hasegawa				
	2002/0022370 A1	02/2002	Sun et al.				
	2002/0033382 A1	03/2002	Kaufman et al.				
	6,375,693 B1	04/2002	Cote et al.				
	6,409,781 B1	06/2002	Wojtczak et al.				
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
OTHER DOCUMENTS						(Including Author, Title, Date, Pertinent Pages, Etc.)	
		Seung-Mahn Lee, et al., "Fundamental Study of Iodate and Iodine Based Slurries for Copper CMP," Mat. Res. Soc. Symp., Vol. 613, ©2000 Materials Research Society, pp. E7.8.1-E7.8.6.					
		PCT International Search Report of 7/30/02.					
EXAMINER			DATE CONSIDERED				